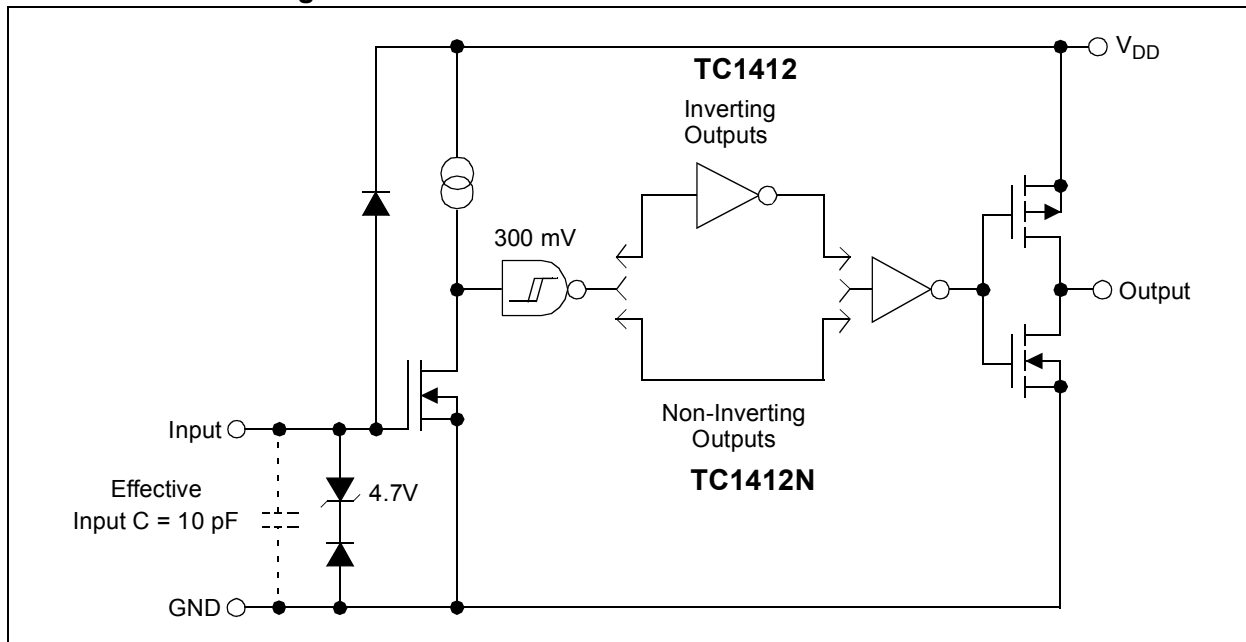


# TC1412/TC1412N

## Functional Block Diagram



## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings †

Supply Voltage ..... +20V  
 Input Voltage .....  $V_{DD} + 0.3V$  to GND – 5.0V  
 Power Dissipation ( $T_A \leq 70^\circ C$ )  
     MSOP ..... 340 mW  
     PDIP ..... 730 mW  
     SOIC ..... 470 mW  
 Storage Temperature Range .....  $-65^\circ C$  to  $+150^\circ C$   
 Maximum Junction Temperature .....  $+150^\circ C$

† Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

## PIN FUNCTION TABLE

Symbol	Description
$V_{DD}$	Supply input, 4.5V to 16V
INPUT	Control input
NC	No connection
GND	Ground
GND	Ground
OUTPUT	CMOS push-pull output, common to pin 7
OUTPUT	CMOS push-pull output, common to pin 6
$V_{DD}$	Supply input, 4.5V to 16V

## DC ELECTRICAL CHARACTERISTICS

**Electrical Specifications:** Unless otherwise noted, over operating temperature range with  $4.5V \leq V_{DD} \leq 16V$ . Typical values are measured at  $T_A = +25^\circ C$ ,  $V_{DD} = 16V$ .

Parameters	Sym	Min	Typ	Max	Units	Conditions
<b>Input</b>						
Logic '1', High Input Voltage	$V_{IH}$	2.0	—	—	V	
Logic '0', Low Input Voltage	$V_{IL}$	—	—	0.8	V	
Input Current	$I_{IN}$	-1.0 -10	— —	1.0 10	$\mu A$	$0V \leq V_{IN} \leq V_{DD}$ , $T_A = +25^\circ C$ $-40^\circ C \leq T_A \leq +85^\circ C$
<b>Output</b>						
High Output Voltage	$V_{OH}$	$V_{DD} - 0.025$	—	—	V	DC Test
Low Output Voltage	$V_{OL}$	—	—	0.025	V	DC Test
Output Resistance	$R_O$	— — —	4 5 5	6 7 7	$\Omega$	$V_{DD} = 16V$ , $I_O = 10 mA$ , $T_A = +25^\circ C$ $0^\circ C \leq T_A \leq +70^\circ C$ $-40^\circ C \leq T_A \leq +85^\circ C$
Peak Output Current	$I_{PK}$	—	2.0	—	A	$V_{DD} = 16V$
Latch-Up Protection Withstand Reverse Current	$I_{REV}$	—	0.5	—	A	Duty cycle $\leq 2\%$ , $t \leq 300 \mu sec$ , $V_{DD} = 16V$
<b>Switching Time (Note 1)</b>						
Rise Time	$t_R$	— — —	18 20 22	26 31 31	nsec	$T_A = +25^\circ C$ $0^\circ C \leq T_A \leq +70^\circ C$ $-40^\circ C \leq T_A \leq +85^\circ C$ , <b>Figure 4-1</b>
Fall Time	$t_F$	— — —	18 20 22	26 31 31	nsec	$T_A = +25^\circ C$ $0^\circ C \leq T_A \leq +70^\circ C$ $-40^\circ C \leq T_A \leq +85^\circ C$ , <b>Figure 4-1</b>

**Note 1:** Switching times ensured by design.

# TC1412/TC1412N

## DC ELECTRICAL CHARACTERISTICS (CONTINUED)

<b>Electrical Specifications:</b> Unless otherwise noted, over operating temperature range with $4.5V \leq V_{DD} \leq 16V$ . Typical values are measured at $T_A = +25^{\circ}C$ , $V_{DD} = 16V$ .						
Parameters	Sym	Min	Typ	Max	Units	Conditions
Delay Time	$t_{D1}$	—	35	45	nsec	$T_A = +25^{\circ}C$ ,
		—	40	50		$0^{\circ}C \leq T_A \leq +70^{\circ}C$
		—	40	50		$-40^{\circ}C \leq T_A \leq +85^{\circ}C$ , <b>Figure 4-1</b>
Delay Time	$t_{D2}$	—	35	45	nsec	$T_A = +25^{\circ}C$
		—	40	50		$0^{\circ}C \leq T_A \leq +70^{\circ}C$
		—	40	50		$-40^{\circ}C \leq T_A \leq +85^{\circ}C$ , <b>Figure 4-1</b>
<b>Power Supply</b>						
Power Supply Current	$I_S$	—	0.5	1.0	mA	$V_{IN} = 3V$ , $V_{DD} = 16V$
		—	0.1	0.15		$V_{IN} = 0V$

**Note 1:** Switching times ensured by design.

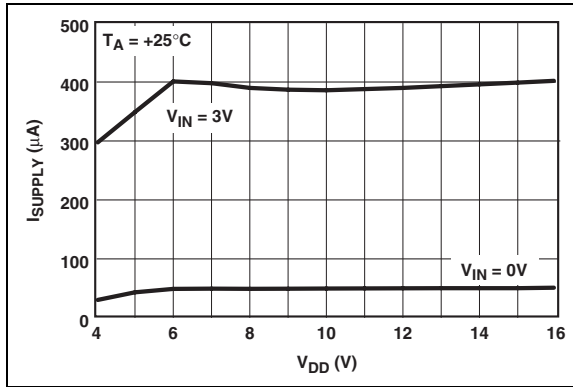
## TEMPERATURE CHARACTERISTICS

<b>Electrical Specifications:</b> Unless otherwise noted, all parameters apply with $4.5V \leq V_{DD} \leq 18V$ .						
Parameters	Sym	Min	Typ	Max	Units	Conditions
<b>Temperature Ranges</b>						
Specified Temperature Range (C)	$T_A$	0	—	+70	$^\circ C$	
Specified Temperature Range (E)	$T_A$	-40	—	+85	$^\circ C$	
Maximum Junction Temperature	$T_J$	—	—	+150	$^\circ C$	
Storage Temperature Range	$T_A$	-65	—	+150	$^\circ C$	
<b>Package Thermal Resistances</b>						
Thermal Resistance, 8L-MSOP	$\theta_{JA}$	—	206	—	$^\circ C/W$	
Thermal Resistance, 8L-PDIP	$\theta_{JA}$	—	125	—	$^\circ C/W$	
Thermal Resistance, 8L-SOIC	$\theta_{JA}$	—	155	—	$^\circ C/W$	

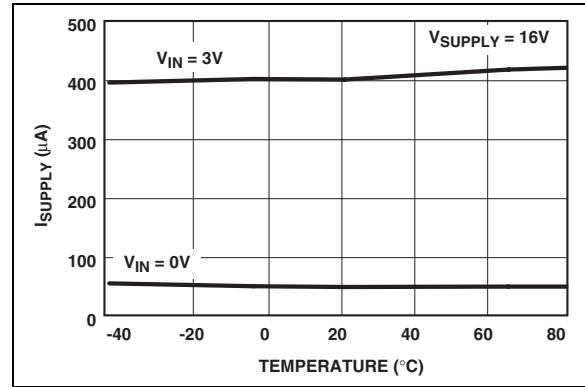
## 2.0 TYPICAL PERFORMANCE CURVES

**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

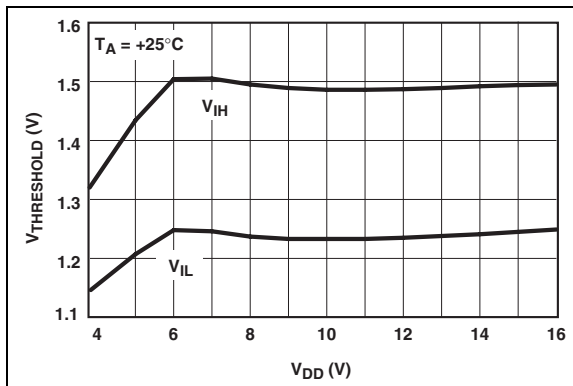
**Note:** Unless otherwise indicated, over operating temperature range with  $4.5V \leq V_{DD} \leq 16V$ .



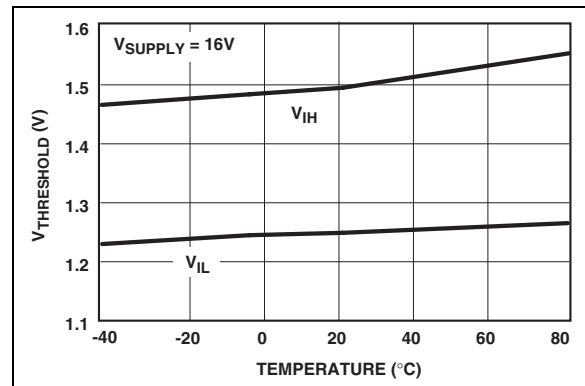
**FIGURE 2-1:** Quiescent Supply Current vs. Supply Voltage.



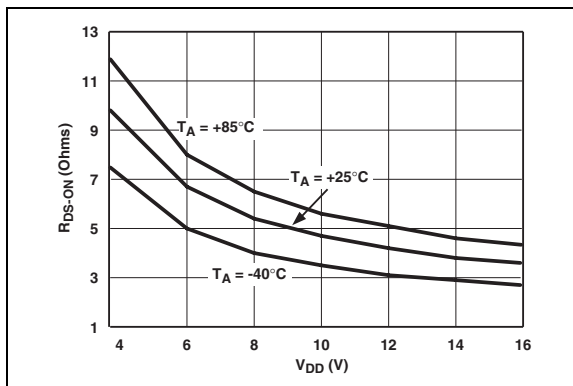
**FIGURE 2-4:** Quiescent Supply Current vs. Temperature.



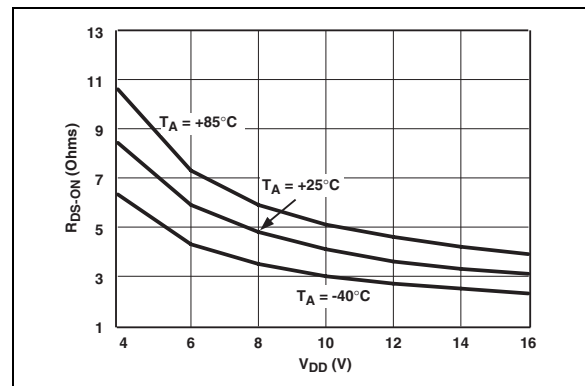
**FIGURE 2-2:** Input Threshold vs. Supply Voltage.



**FIGURE 2-5:** Input Threshold vs. Temperature.



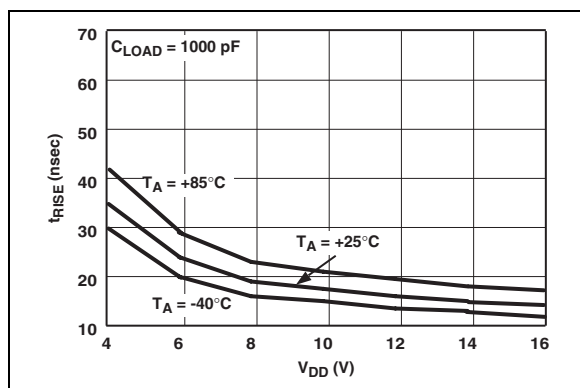
**FIGURE 2-3:** High-State Output Resistance vs. Supply Voltage.



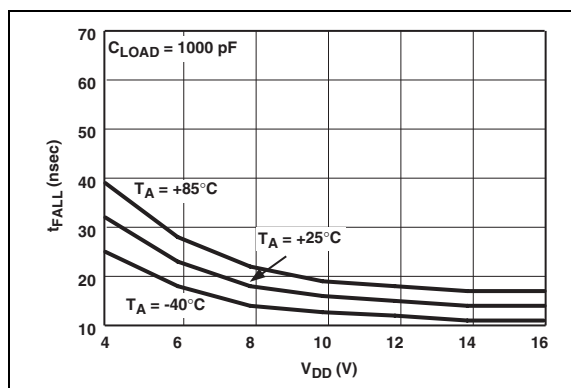
**FIGURE 2-6:** Low-State Output Resistance vs. Supply Voltage.

# TC1412/TC1412N

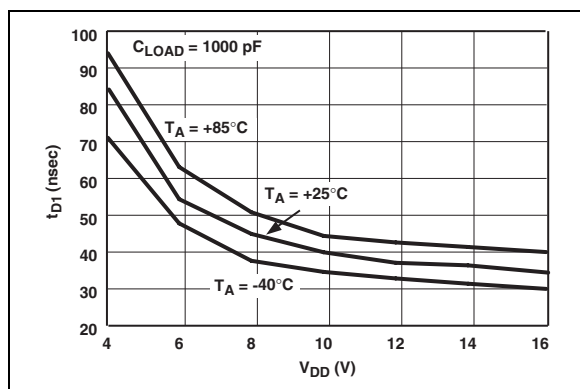
**Note:** Unless otherwise indicated, over operating temperature range with  $4.5V \leq V_{DD} \leq 16V$ .



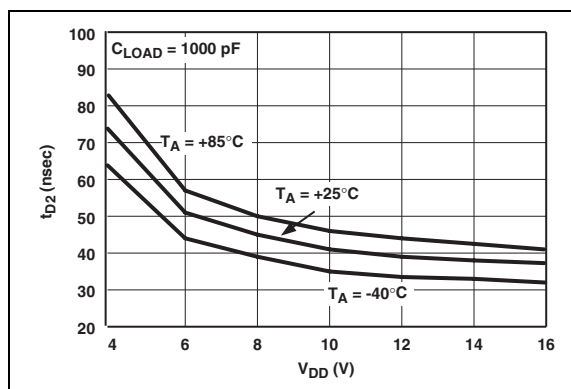
**FIGURE 2-7:** Rise Time vs. Supply Voltage.



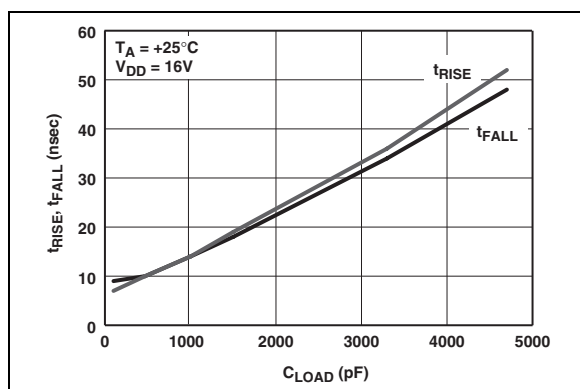
**FIGURE 2-10:** Fall Time vs. Supply Voltage.



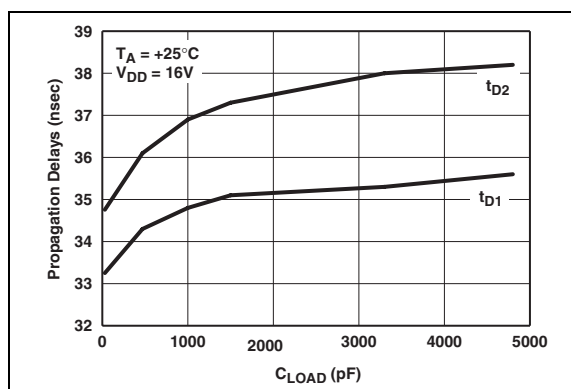
**FIGURE 2-8:** Propagation Delay vs. Supply Voltage.



**FIGURE 2-11:** Propagation Delay vs. Supply Voltage.



**FIGURE 2-9:** Rise and Fall Times vs. Capacitive Load.



**FIGURE 2-12:** Propagation Delays vs. Capacitive Load.

## 3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

**TABLE 3-1: PIN FUNCTION TABLE**

Pin No.	Symbol	Description
1	V <sub>DD</sub>	Supply input, 4.5V to 16V
2	INPUT	Control input
3	NC	No connection
4	GND	Ground
5	GND	Ground
6	OUTPUT	CMOS push-pull output, common to pin 7
7	OUTPUT	CMOS push-pull output, common to pin 6
8	V <sub>DD</sub>	Supply input, 4.5V to 16V

### 3.1 Supply Input (V<sub>DD</sub>)

The V<sub>DD</sub> input is the bias supply for the MOSFET driver and is rated for 4.5V to 16V with respect to the ground pin. The V<sub>DD</sub> input should be bypassed to ground with a local ceramic capacitor. The value of the capacitor should be chosen based on the capacitive load that is being driven. A value of 1.0  $\mu$ F is suggested.

### 3.2 Control Input (INPUT)

The MOSFET driver input is a high-impedance, TTL/CMOS-compatible input. The input has 300 mV of hysteresis between the high and low thresholds which prevents output glitching even when the rise and fall time of the input signal is very slow.

### 3.3 CMOS Push-Pull Output (OUTPUT)

The MOSFET driver output is a low-impedance, CMOS push-pull style output, capable of driving a capacitive load with 2A peak currents.

### 3.4 Ground (GND)

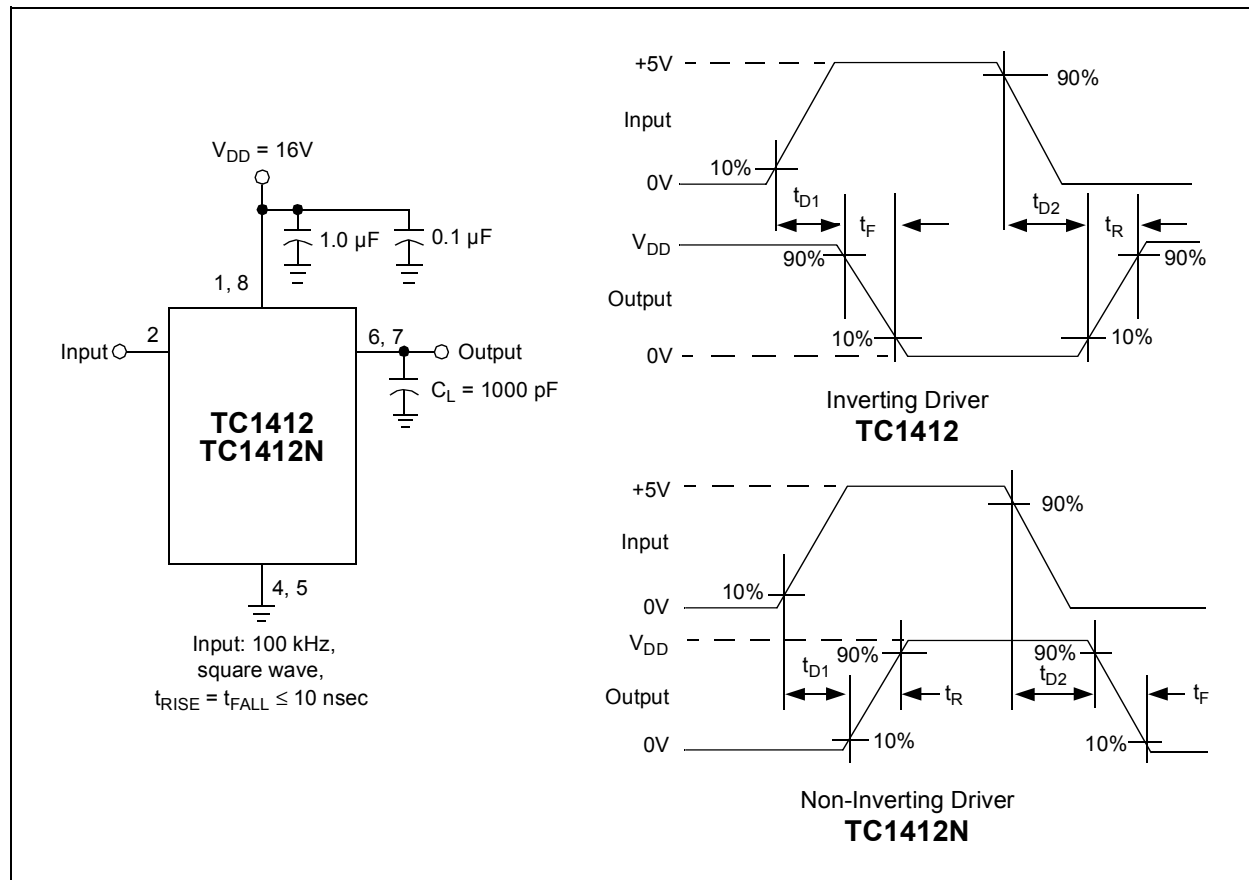
The ground pins are the return path for the bias current and for the high peak currents that discharge the load capacitor. The ground pins should be tied into a ground plane or have very short traces to the bias supply source return.

### 3.5 No Connect (NC)

No internal connection.

# TC1412/TC1412N

## 4.0 APPLICATION INFORMATION

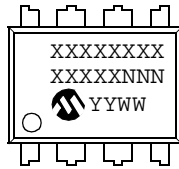


**FIGURE 4-1:** Switching Time Test Circuit.

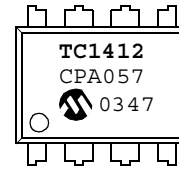
## 5.0 PACKAGING INFORMATION

### 5.1 Package Marking Information

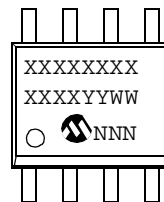
8-Lead PDIP (300 mil)



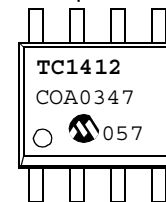
Example:



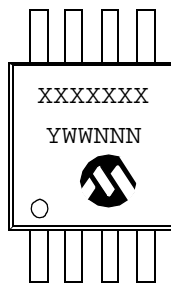
8-Lead SOIC (150 mil)



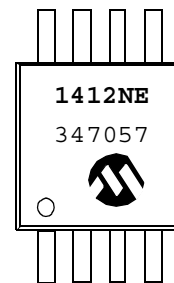
Example:



8-Lead MSOP



Example:



<b>Legend:</b>	XX...X	Customer specific information*
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code

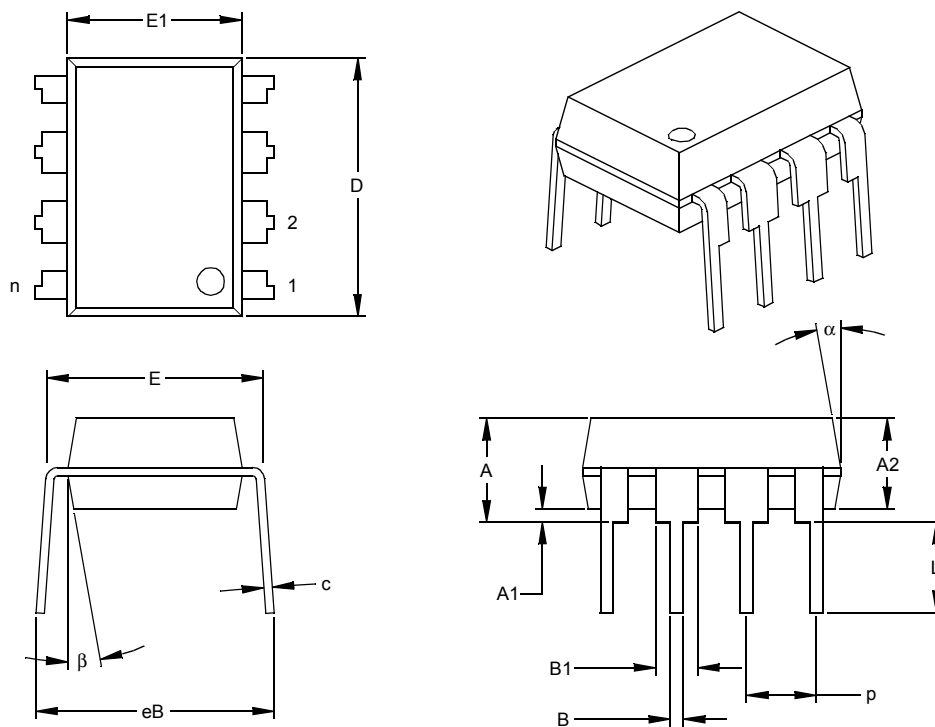
**Note:** In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.

- \* Standard marking consists of Microchip part number, year code, week code, traceability code (facility code, mask rev#, and assembly code). For marking beyond this, certain price adders apply. Please check with your Microchip Sales Office.



# TC1412/TC1412N

## 8-Lead Plastic Dual In-line (PA) – 300 mil (PDIP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

\* Controlling Parameter

§ Significant Characteristic

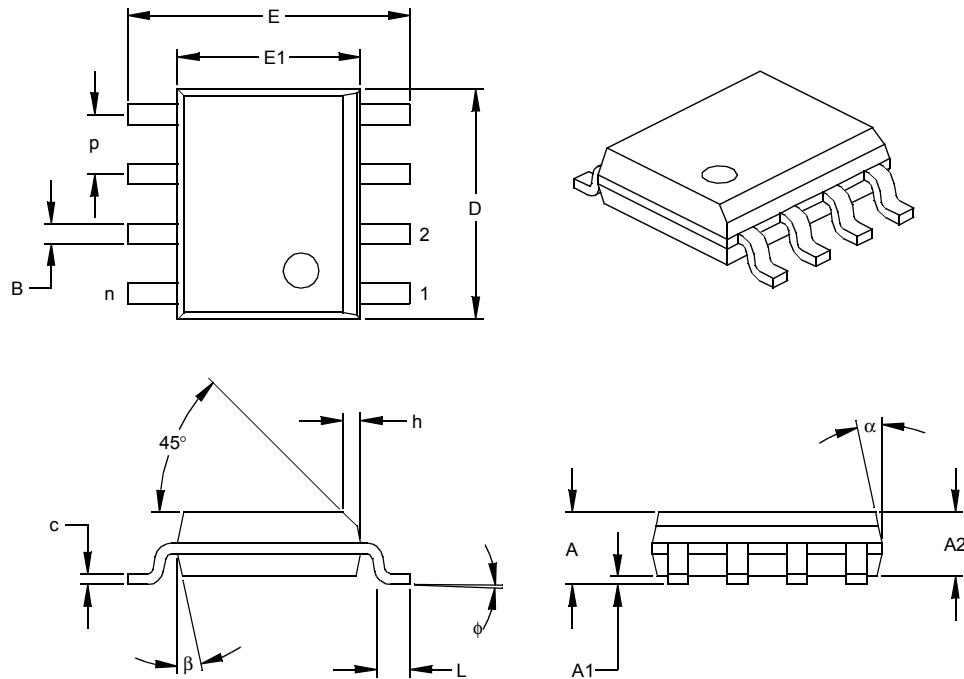
Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-001

Drawing No. C04-018

## 8-Lead Plastic Small Outline (OA) – Narrow, 150 mil (SOIC)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.050			1.27	
Overall Height	A	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.008	.009	.010	0.20	0.23	0.25
Lead Width	B	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

\* Controlling Parameter  
§ Significant Characteristic

### Notes:

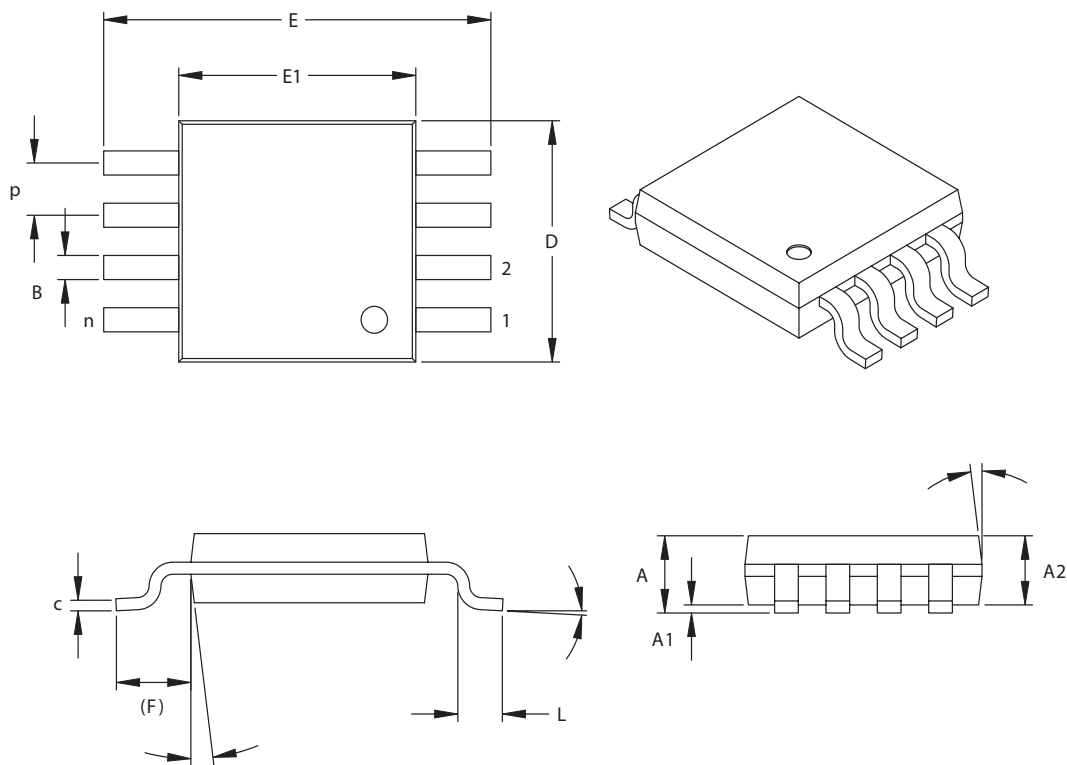
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-012

Drawing No. C04-057

# TC1412/TC1412N

## 8-Lead Plastic Micro Small Outline Package (UA) (MSOP)



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p	.026 BSC			0.65 BSC		
Overall Height	A	-	-	.043	-	-	1.10
Molded Package Thickness	A2	.030	.033	.037	0.75	0.85	0.95
Standoff	A1	.000	-	.006	0.00	-	0.15
Overall Width	E	.193 BSC			4.90 BSC		
Molded Package Width	E1	.118 BSC			3.00 BSC		
Overall Length	D	.118 BSC			3.00 BSC		
Foot Length	L	.016	.024	.031	0.40	0.60	0.80
Footprint (Reference)	F	.037 REF			0.95 REF		
Foot Angle		0°	-	8°	0°	-	8°
Lead Thickness	c	.003	.006	.009	0.08	-	0.23
Lead Width	B	.009	.012	.016	0.22	-	0.40
Mold Draft Angle Top		5°	-	15°	5°	-	15°
Mold Draft Angle Bottom		5°	-	15°	5°	-	15°

\*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MO-187

Drawing No. C04-111

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>X</u>	<u>/XX</u>
Device	Temperature Range	Package
Device:	TC1412: 2 A Single MOSFET Driver, Inverting TC1412N: 2 A Single MOSFET Driver, Non-Inverting	
Temperature Range:	C = 0°C to +70°C E = -40°C to +85°C	
Package:	OA = Plastic SOIC, (150 mil Body), 8-lead OA713 = Plastic SOIC, (150 mil Body), 8-lead (Tape and Reel) UA = Plastic Micro Small Outline (MSOP), 8-lead * UA713 = Plastic Micro Small Outline (MSOP), 8-lead * (Tape and Reel) PA = Plastic DIP (300 mil Body), 8-lead * MSOP package is only available in E-Temp.	

**Examples:**

- a) TC1412COA: 2A Single MOSFET driver, SOIC package, 0°C to +70°C.
- b) TC1412CPA: 2A Single MOSFET driver, PDIP package, 0°C to +70°C.
- c) TC1412EUA713: Tape and Reel, 2A Single MOSFET driver, MSOP package, -40°C to +85°C.

- a) TC1412NCPA: 2A Single MOSFET driver, PDIP package, 0°C to +70°C.
- b) TC1412NEPA: 2A Single MOSFET driver, PDIP package, -40°C to +85°C.
- c) TC1412NEUA: 2A Single MOSFET driver, MSOP package, -40°C to +85°C.

## Sales and Support

### Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
3. The Microchip Worldwide Site ([www.microchip.com](http://www.microchip.com))

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

### Customer Notification System

Register on our web site ([www.microchip.com/cn](http://www.microchip.com/cn)) to receive the most current information on our products.

# TC1412/TC1412N

---

NOTES:

---

**Note the following details of the code protection feature on Microchip devices:**

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

---

Information contained in this publication regarding device applications and the like is intended through suggestion only and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. No representation or warranty is given and no liability is assumed by Microchip Technology Incorporated with respect to the accuracy or use of such information, or infringement of patents or other intellectual property rights arising from such use or otherwise. Use of Microchip's products as critical components in life support systems is not authorized except with express written approval by Microchip. No licenses are conveyed, implicitly or otherwise, under any intellectual property rights.

#### Trademarks

The Microchip name and logo, the Microchip logo, KEELOQ, MPLAB, PIC, PICmicro, PICSTART, PRO MATE and PowerSmart are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.


FilterLab, microID, MXDEV, MXLAB, PICMASTER, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

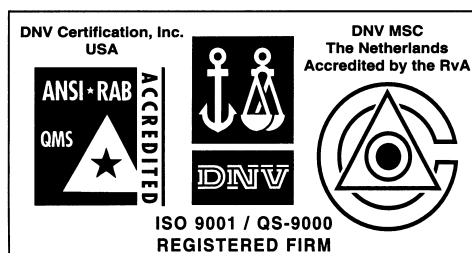
Accuron, Application Maestro, dsPIC, dsPICDEM, dsPICDEM.net, ECONOMONITOR, FanSense, FlexROM, fuzzyLAB, In-Circuit Serial Programming, ICSP, ICEPIC, microPort, Migratable Memory, MPASM, MPLIB, MPLINK, MPSIM, PICC, PICkit, PICDEM, PICDEM.net, PowerCal, PowerInfo, PowerMate, PowerTool, rLAB, rPIC, Select Mode, SmartSensor, SmartShunt, SmartTel and Total Endurance are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

Serialized Quick Turn Programming (SQTP) is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2003, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.



*Microchip received QS-9000 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona in July 1999 and Mountain View, California in March 2002. The Company's quality system processes and procedures are QS-9000 compliant for its PICmicro® 8-bit MCUs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, non-volatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001 certified.*



## WORLDWIDE SALES AND SERVICE

### AMERICAS

#### Corporate Office

2355 West Chandler Blvd.  
Chandler, AZ 85224-6199  
Tel: 480-792-7200 Fax: 480-792-7277  
Technical Support: 480-792-7627  
Web Address: <http://www.microchip.com>

#### Atlanta

3780 Mansell Road, Suite 130  
Alpharetta, GA 30022  
Tel: 978-640-0034 Fax: 770-640-0307

#### Boston

2 Lan Drive, Suite 120  
Westford, MA 01886  
Tel: 978-692-3848 Fax: 978-692-3821

#### Chicago

333 Pierce Road, Suite 180  
Itasca, IL 60143  
Tel: 630-285-0071 Fax: 630-285-0075

#### Dallas

4570 Westgrove Drive, Suite 160  
Addison, TX 75001  
Tel: 972-818-7423 Fax: 972-818-2924

#### Detroit

Tri-Atria Office Building  
32255 Northwestern Highway, Suite 190  
Farmington Hills, MI 48334  
Tel: 248-538-2250 Fax: 248-538-2260

#### Kokomo

2767 S. Albright Road  
Kokomo, IN 46902  
Tel: 765-864-8360 Fax: 765-864-8387

#### Los Angeles

18201 Von Karman, Suite 1090  
Irvine, CA 92612  
Tel: 949-263-1888 Fax: 949-263-1338

#### Phoenix

2355 West Chandler Blvd.  
Chandler, AZ 85224-6199  
Tel: 480-792-7966 Fax: 480-792-4338

#### San Jose

Microchip Technology Inc.  
2107 North First Street, Suite 590  
San Jose, CA 95131  
Tel: 408-436-7950 Fax: 408-436-7955

#### Toronto

6285 Northam Drive, Suite 108  
Mississauga, Ontario L4V 1X5, Canada  
Tel: 905-673-0699 Fax: 905-673-6509

### ASIA/PACIFIC

#### Australia

Microchip Technology Australia Pty Ltd  
Marketing Support Division  
Suite 22, 41 Rawson Street  
Epping 2121, NSW  
Australia  
Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

#### China - Beijing

Microchip Technology Consulting (Shanghai)  
Co., Ltd., Beijing Liaison Office  
Unit 915  
Bei Hai Wan Tai Bldg.  
No. 6 Chaoyangmen Beidajie  
Beijing, 100027, No. China  
Tel: 86-10-85282100 Fax: 86-10-85282104

#### China - Chengdu

Microchip Technology Consulting (Shanghai)  
Co., Ltd., Chengdu Liaison Office  
Rm. 2401-2402, 24th Floor,  
Ming Xing Financial Tower  
No. 88 TIDU Street  
Chengdu 610016, China  
Tel: 86-28-86766200 Fax: 86-28-86766599

#### China - Fuzhou

Microchip Technology Consulting (Shanghai)  
Co., Ltd., Fuzhou Liaison Office  
Unit 28F, World Trade Plaza  
No. 71 Wusi Road  
Fuzhou 350001, China  
Tel: 86-591-7503506 Fax: 86-591-7503521

#### China - Hong Kong SAR

Microchip Technology Hongkong Ltd.  
Unit 901-6, Tower 2, Metroplaza  
223 Hing Fong Road  
Kwai Fong, N.T., Hong Kong  
Tel: 852-2401-1200 Fax: 852-2401-3431

#### China - Shanghai

Microchip Technology Consulting (Shanghai)  
Co., Ltd.  
Room 701, Bldg. B  
Far East International Plaza  
No. 317 Xian Xia Road  
Shanghai, 200051  
Tel: 86-21-6275-5700 Fax: 86-21-6275-5060

#### China - Shenzhen

Microchip Technology Consulting (Shanghai)  
Co., Ltd., Shenzhen Liaison Office  
Rm. 1812, 18/F, Building A, United Plaza  
No. 5022 Binhe Road, Futian District  
Shenzhen 518033, China  
Tel: 86-755-82901380 Fax: 86-755-82966626

#### China - Qingdao

Rm. B505A, Fullhope Plaza,  
No. 12 Hong Kong Central Rd.  
Qingdao 266071, China  
Tel: 86-532-5027355 Fax: 86-532-5027205

#### India

Microchip Technology Inc.  
India Liaison Office  
Marketing Support Division  
Divyasree Chambers  
1 Floor, Wing A (A3/A4)  
No. 11, O'Shaugnessey Road  
Bangalore, 560 025, India  
Tel: 91-80-2290061 Fax: 91-80-2290062

### Japan

Microchip Technology Japan K.K.  
Benex S-1 6F  
3-18-20, Shinyokohama  
Kohoku-Ku, Yokohama-shi  
Kanagawa, 222-0033, Japan  
Tel: 81-45-471-6166 Fax: 81-45-471-6122

### Korea

Microchip Technology Korea  
168-1, Youngbo Bldg. 3 Floor  
Samsung-Dong, Kangnam-Ku  
Seoul, Korea 135-882  
Tel: 82-2-554-7200 Fax: 82-2-558-5934

### Singapore

Microchip Technology Singapore Pte Ltd.  
200 Middle Road  
#07-02 Prime Centre  
Singapore, 188980  
Tel: 65-6334-8870 Fax: 65-6334-8850

### Taiwan

Microchip Technology (Barbados) Inc.,  
Taiwan Branch  
11F-3, No. 207  
Tung Hua North Road  
Taipei, 105, Taiwan  
Tel: 886-2-2717-1715 Fax: 886-2-2545-0139

### EUROPE

#### Austria

Microchip Technology Austria GmbH  
Durisolstrasse 2  
A-4600 Wels  
Austria  
Tel: 43-7242-2244-399  
Fax: 43-7242-2244-393

#### Denmark

Microchip Technology Nordic ApS  
Regus Business Centre  
Lautrup høj 1-3  
Ballerup DK-2750 Denmark  
Tel: 45-4420-9895 Fax: 45-4420-9910

#### France

Microchip Technology SARL  
Parc d'Activite du Moulin de Massy  
43 Rue du Saule Trapu  
Batiment A - 1er Etage  
91300 Massy, France  
Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

#### Germany

Microchip Technology GmbH  
Steinheilstrasse 10  
D-85737 Ismaning, Germany  
Tel: 49-89-627-144-0  
Fax: 49-89-627-144-44

#### Italy

Microchip Technology SRL  
Via Quasimodo, 12  
20025 Legnano (MI)  
Milan, Italy  
Tel: 39-0331-742611 Fax: 39-0331-466781

#### United Kingdom

Microchip Ltd.  
505 Eskdale Road  
Wokingham  
Berkshire, England RG41 5TU  
Tel: 44-118-921-5869 Fax: 44-118-921-5820